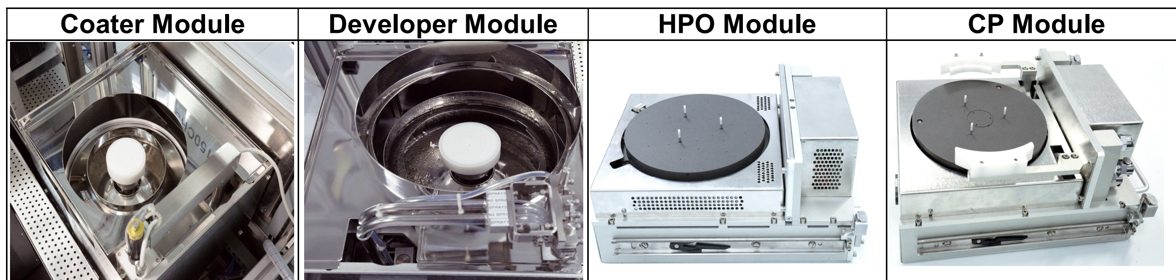
309 Laurelwood Rd #21
Santa Clara, CA 95054
Main: (408)988-7000
Fax: (408)988-7091

PCT-150CRS PG TRACK SYSTEM

STANDARD PRODUCTION or R&D WITH DUAL TRACKS (1 COATER, 1 DEVLOPER) TOOL SET

Please contact Sales sales@picotrack.com for more information

Coater Module	Developer Module	HPO Module	CP Module



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Track System Specification	Description
System designed	US Standard System
System Configuration (*Configuration available upon request)	SYSTEM CONFIGURATION - WAFER SIZE: 6" .WAFER FLOW: RANDOM, SHUTTLE ARM HPO HPO ¦ HPO HPO HPO - CP-CENT. ¦ CP-CENT. - CP ----------- ARM #1 -------- ¦ -------- ARM #2 -------- SEND ¦ SEND COAT (PG) - REC. ¦ REC. - DEV. (PG)
System dimension	Length: 72.5" ; Width: 45" ; Height: 90"
Wafer size (workable dual size)	Up to 6" (150mm) or 4" & 6" auto conversion
Wafer shape	Round/Square/Rectangular/Triangle/Special
Wafer material	Silicon/Sapphire/GaAs/ Ceramic…
Wafer sensor	Optical sensor mapping
System controller	PC & PLC Controller with Windows OS based
Chemical canister cabinet	Solvent (EBR, Cleaning…), developer liquid
Pumps cabinet	Photoresist pumps (IDI, Cybor..), dispenser unit, & photoresist bottles
PG Mixer Cabinet	3 PG bottle (900ml), roller contolled by PLC & motor driver
Indexer wafer cassettes capacity	4 or more (available upon request)
Shuttle Robot Arm	2 Robot Arm and dual end effectors
System Fan Filter Unit (FFU)	optional
System SECs/GEM	optional
Coater	**1 module**
Catch Cup Set	Up/down motion
Spindle Unit	Fixed position
Maximum spin speed	7000 rpm
Spin motor type	Servo
Spin speed accuracy	± 3 rpm
Acceleration range	0-50000 rpm/sec
Dispense arm accuracy	± 0.1 mm
Wafer centering	± 0.1 mm
Dispense arm motion control	Stepper motor drive and rotation
Dispense arm # 1 & nozzles	3x or more (3/16" or 1/4" OD) (Standard)
Dispense arm # 2 & nozzles	Optional
Dispense method	Static, and radial with PG canister or pump
Pre-dispense function	Yes
Bottom EBR	Yes
Catch-cup rinse(CCR)	Optional
Cleaning tip nozzle	Optional
Humidity & Temperature control	Optional
Photoresist temperature control	Optional (≤ 1°C; 10-50°C range)
Developer	**1 module**
Catch Cup Set	Up/down motion
Spindle Unit	Fixed position
Maximum spin speed	7000 rpm
Spin motor type	Servo
Spin speed accuracy	± 3 rpm

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Acceleration range	0-50000 rpm/sec
Spin direction	Clockwise (+) & counter clockwise (-)
Dispense arm motion control	Stepper motor drive and rotation
Dispense arm accuracy	± 0.1 mm
Wafer centering tolerance	± 0.1 mm
Dispense arm # 1 nozzles	2 Sprays, 1 Stream nozzle (Standard)
Dispense arm # 2 nozzles	Optional
Negative developer nozzles	Coin or fan spray with N2 air assist (Upon request)
Developer dispense type	Stream, Puddle, Fan spray, Cone spray….
Dispense method	Static, radial and sweep with pressurized canister or liquid pump
DI water top and back side rinse	Yes
N2 Air Ring back side	Yes
N2 Blow-off top nozzle	Optional
Developer liquid Temp. controller	Optional (≤ 1°C; 10-50°C range)
Hot Plate Oven (HPO)	**5 modules (Stack up)**
HPO block type	Aluminum anodized with vacuum slots or standoff proximity
HPO Temperature controller	Watlow P.I.D with over heating protection
Temperature thermal probe	RTD or TC
Temperature range	25-250°C, Δt: 50°C ≤ 200s (>250°C option)
Temperature uniformity	± 1°C (25-150°C), ± 2°C (151-250°C)
Wafer Carrier	3 pins controlled by stepper motor
Bake method	Contact/ Proximity bake/ or fixed proximity
Chill Plate & Centering (CP-CENT)	**2 or 4 modules (Stack up)**
Chill Plate block type	Aluminum anodized with vacuum slots
Chill Plate Temperature control	House cooling water with flowmeter (18°C to 30°C)
Chill method	Contact
Cooling Water Temperature controller	Optional
Wafer carrier	3 pins controlled by stepper motor and cylinder
Wafer Centering	Integrated